ELECTRONICALLY FILED ON 25 SEPTEMBER 2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Marcos Karnezos

Application No.: 10/632,568

Filed: 02 August 2003

Title: Semiconductor Multi-Package Module Having Wire Bond Interconnect Between Stacked Packages And Having Enhanced Heat Dissipation Attorney Docket No.: CPAC 1017-3 D1

Examiner: Douglas M. Menz

Group: 2891

Confirmation No.: 2603

Customer No. 22470

INFORMATION DISCLOSURE STATEMENT

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

It is requested that the information identified in this statement be considered by the Examiner and made of record in the above-identified application. This statement is not intended to represent that a search has been made or that the information cited in the statement is, or is considered to be, material to patentability as defined in 37 C.F.R. 1.56.

Enclosed with this statement is a Form PTO/SB/08A. The Examiner is requested to initial the form and return it to the undersigned in accordance with M.P.E.P. 609.

Also enclosed with this statement is a copy of each cited document as required by 37 C.F.R. 1.98. However, since this application was filed after June 30, 2003, copies of U. S. Patents and U. S. Patent Application Publications are not enclosed. (See O. G. Notice of August 5, 2003.)

This statement should be considered under 37 C.F.R. 1.97(c) because it is being filed before the mailing date of a FINAL office action, a Notice of Allowance, or an action that otherwise closes prosecution in the subject application, whichever occurs first, AND:

This statement is accompanied by the \$180 fee set forth in 37 C.F.R. 1.17(p).

Fee Authorization. The Commissioner is hereby authorized to charge any additional fees or credit any overpayment associated with this communication to Deposit Account No. 50-0869 (CPAC 1017-3 D1). A duplicate copy of this authorization is enclosed.

Respectfully submitted, Haynes Beffel & Wolfeld LLP

Date: 25 September 2006

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Substitute for form PTO/SB/08A

Sheet 1 of 1

Application Number	10/632,568	
Filing Date	02 August 2003	
First Named Inventor	Marcos Karnezos	
Art Unit	2891	
Examiner Name	Douglas M. Menz	
Attorney Docket Number	CPAC 1017-3	

U.S. PATENT DOCUMENTS

Examiner's Initials	Patent No. Number-Kind Code	Pub. Date MM-DD- YYYY	Name	Pages, Cols, Lines of Relevant Passages or Figures
	US 6,930,378	08-16-2005	St. Amand et al.	
	US 6,933,598	08-23-2005	Karnezos	
	US 7,034,387	04-25-2006	Karnezos	
	US 7,045,887	05-16-2006	Karnezos	
	US 7,049,691	05-23-2006	Karnezos	
	US 7,053,476	05-30-2006	Karnezos	
	US 7,057,269	06-06-2006	Karnezos	
	US 7,061,088	06-13-2006	Karnezos	
	US 7,064,426	06-20-2006	Karnezos	
	US 7,071,568	07-04-2006	St. Amand et al.	
	US 7,081,678	07-25-2006	Tsai	
	US 2006/0138631	06-29-2006	Tao et al.	

Examiner Signature	Date Considered	